

22. (Unchanged) The substrate processing system according to claim 20 wherein the dielectric film is to be deposited over a plurality of stepped surfaces formed on the substrate having gaps formed between adjacent ones of the stepped surfaces and wherein the first portion of the film partially fills the gaps.

This application is a Divisional Patent Application of Appl. No. 09/648,395 filed August 24, 2000 ("the parent application"). On June 5, 2001, Claims 17-22 were subjected to an oral restriction requirement by the Examiner and were withdrawn when Applicant's representative elected Claims 1-16. Accordingly, Claims 17-22 are presented in this Divisional Application.

CONCLUSION

In view of the foregoing, Applicants believe all claims now pending in this Application are in condition for allowance. The issuance of a formal Notice of Allowance at an early date is respectfully requested.

If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at 303-571-4000.

Respectfully submitted,



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